

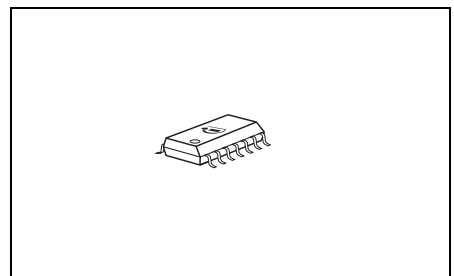
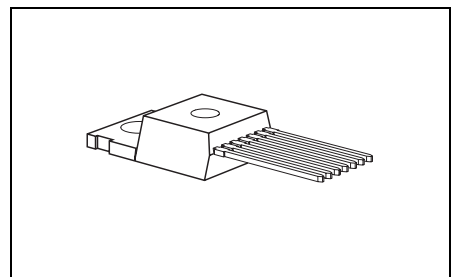
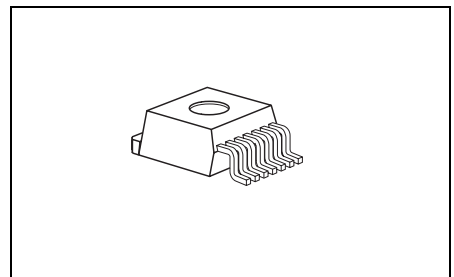
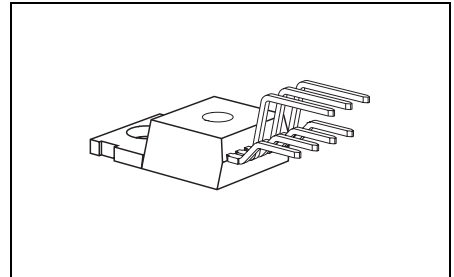


Features

- Output voltage tolerance $\leq \pm 2\%$
- 400 mA output current capability
- Low-drop voltage
- Very low standby current consumption
- Input voltage up to 40 V
- Overvoltage protection up to 60 V (≤ 400 ms)
- Reset function down to 1 V output voltage
- ESD protection up to 2000 V
- Adjustable reset time
- On/off logic
- Overtemperature protection
- Reverse polarity protection
- Short-circuit proof
- Wide temperature range
- Suitable for use in automotive electronics
- Green Product (RoHS compliant)
- AEC Qualified

Functional Description

TLE 4267 is a 5-V low drop voltage regulator for automotive applications in the PG-TO220-7 or PG-DSO-14-30 package. It supplies an output current of > 400 mA. The IC is shortcircuit-proof and has an overtemperature protection circuit.



Type	Package	Type	Package
TLE 4267	PG-TO220-7-11	TLE 4267 S	PG-TO220-7-12
TLE 4267 G	PG-TO263-7-1	TLE 4267 GM	PG-DSO-14-30

Application

The IC regulates an input voltage V_I in the range of $5.5\text{ V} < V_I < 40\text{ V}$ to a nominal output voltage of $V_Q = 5.0\text{ V}$. A reset signal is generated for an output voltage of $V_Q < V_{RT}$ (typ. 4.5 V). The reset delay can be set with an external capacitor. The device has two logic inputs. A voltage of $V_{E2} > 4.0\text{ V}$ given to the E2-pin (e.g. by ignition) turns the device on. Depending on the voltage on pin E6 the IC may be hold in active-state even if V_{E2} goes to low level. This makes it simple to implement a self-holding circuit without external components. When the device is turned off, the output voltage drops to 0 V and current consumption tends towards $0\text{ }\mu\text{A}$.

Design Notes for External Components

The input capacitor C_I is necessary for compensation of line influences. The resonant circuit consisting of lead inductance and input capacitance can be damped by a resistor of approx. $1\text{ }\Omega$ in series with C_I . The output capacitor is necessary for the stability of the regulating circuit. Stability is guaranteed at values of $\geq 22\text{ }\mu\text{F}$ and an ESR of $\leq 3\text{ }\Omega$ within the operating temperature range.

Circuit Description

The control amplifier compares a reference voltage, which is kept highly accurate by resistance adjustment, to a voltage that is proportional to the output voltage and drives the base of the series transistor via a buffer. Saturation control as a function of the load current prevents any over-saturating of the power element.

The reset output RO is in high-state if the voltage on the delay capacitor C_D is greater or equal V_{UD} . The delay capacitance C_D is charged with the current I_D for output voltages greater than the reset threshold V_{RT} . If the output voltage gets lower than V_{RT} a fast discharge of the delay capacitor C_D sets in and as soon as V_{CD} gets lower than V_{LD} the reset output RO is set to low-level (see [Figure 6](#)). The reset delay can be set within wide range by dimensioning the capacitance of the external capacitor.

Table 1 Truth Table for Turn-ON/Turn-OFF Logic

E2, Inhibit	E6, Hold	V_Q	Remarks
L	X	OFF	Initial state, Inhibit internally pulled-up
H	X	ON	Regulator switched on via Inhibit, by ignition for example
H	L	ON	Hold clamped active to ground by controller while Inhibit is still high
X	L	ON	Previous state remains, even ignition is shut off: self-holding state
L	L	ON	Ignition shut off while regulator is in self-holding state
L	H	OFF	Regulator shut down by releasing of Hold while Inhibit remains Low, final state. No active clamping required by external self-holding circuit (μC) to keep regulator in off-state.

Inhibit: E2 Enable function, active High

Hold: E6 Hold and release function, active Low

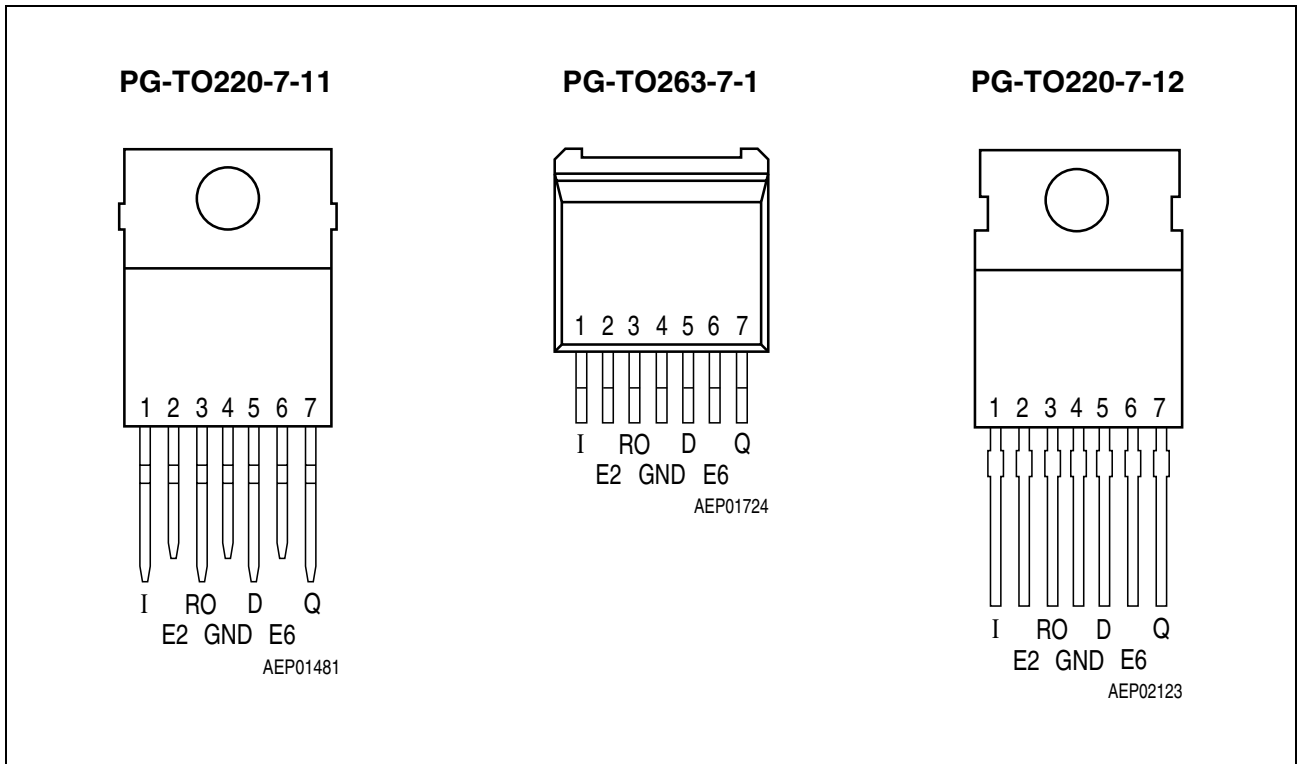


Figure 1 Pin Configuration (top view)

Table 2 Pin Definitions and Functions

Pin	Symbol	Function
1	I	Input ; block to ground directly at the IC by a ceramic capacitor
2	E2	Inhibit ; device is turned on by High signal on this pin; internal pull-down resistor of 100 kΩ
3	RO	Reset Output ; open-collector output internally connected to the output via a resistor of 30 kΩ
4	GND	Ground ; connected to rear of chip
5	D	Reset Delay ; connect via capacitor to GND
6	E6	Hold ; see Table 1 for function; this input is connected to output voltage via a pull-up resistor of 50 kΩ
7	Q	5-V Output ; block to GND with 22-μF capacitor, ESR < 3 Ω

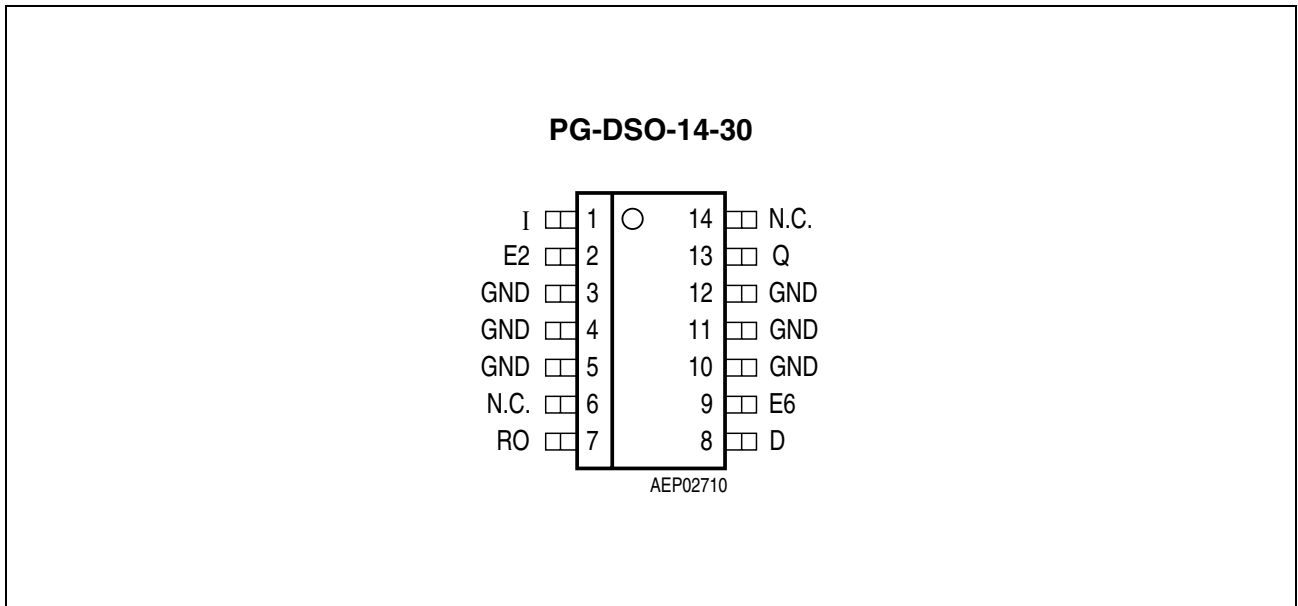


Figure 2 Pin Configuration (top view)

Table 3 Pin Definitions and Functions

Pin	Symbol	Function
1	I	Input ; block to ground directly at the IC by a ceramic capacitor
2	E2	Inhibit ; device is turned on by High signal on this pin; internal pull-down resistor of 100 kΩ
7	RO	Reset Output ; open-collector output internally connected to the output via a resistor of 30 kΩ
3, 4, 5, 10, 11, 12	GND	Ground ; connected to rear of chip
8	D	Reset Delay ; connect with capacitor to GND for setting delay
9	E6	Hold ; see Table 1 for function; this input is connected to output voltage via a pull-up resistor of 50 kΩ
13	Q	5-V Output ; block to GND with 22-μF capacitor, ESR ≤ 3 Ω
6, 14	N.C.	Not Connected

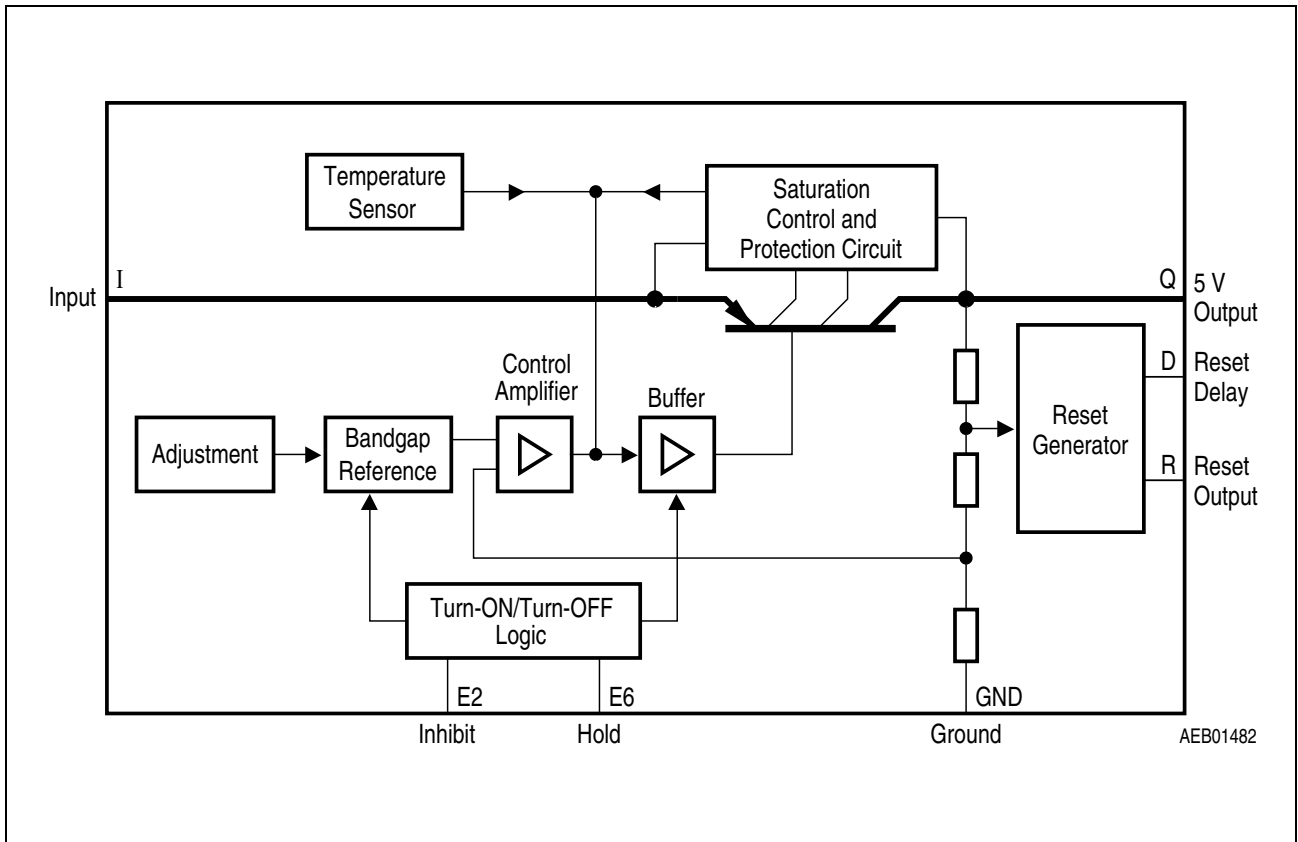


Figure 3 Block Diagram

Table 4 Absolute Maximum Ratings

$T_J = -40$ to 150 °C

Parameter	Symbol	Limit Values		Unit	Notes
		Min.	Max.		
Input					
Voltage	V_I	-42	42	V	–
Voltage	V_I	–	60	V	$t \leq 400$ ms
Current	I_I	–	–	–	internally limited
Reset Output					
Voltage	V_{RO}	-0.3	7	V	–
Current	I_{RO}	–	–	–	internally limited
Reset Delay					
Voltage	V_D	-0.3	42	V	–
Current	I_D	–	–	–	–
Output					
Voltage	V_Q	-0.3	7	V	–
Current	I_Q	–	–	–	internally limited
Inhibit					
Voltage	V_{E2}	-42	42	V	–
Current	I_{E2}	-5	5	mA	$t \leq 400$ ms
Hold					
Voltage	V_{E6}	-0.3	7	V	–
Current	I_{E6}	–	–	mA	internally limited
GND					
Current	I_{GND}	-0.5	–	A	–
Temperatures					
Junction temperature	T_J	–	150	°C	–
Storage temperature	T_{stg}	-50	150	°C	–

Table 5 Operating Range

Parameter	Symbol	Limit Values		Unit	Notes
		Min.	Max.		
Input voltage	V_I	5.5	40	V	see diagram
Junction temperature	T_J	-40	150	°C	–

Thermal Resistance

Junction ambient	R_{thja}	–	65	K/W	PG-TO220-7-11 package
Junction-case	R_{thjc}	–	6	K/W	PG-TO220-7-11 package
Junction-case	Z_{thjc}	–	2	K/W	$T < 1$ ms PG-TO220-7-11 package
Junction ambient	R_{thja}	–	70	K/W	PG-TO263-7-1 (SMD) package
Junction-case	R_{thjc}	–	6	K/W	PG-TO263-7-1 (SMD) package
Junction-case	Z_{thjc}	–	2	K/W	$T < 1$ ms PG-TO263-7-1 (SMD) package
Junction ambient	R_{thja}	–	65	K/W	PG-TO220-7-12 package
Junction-case	R_{thjc}	–	6	K/W	PG-TO220-7-12 package
Junction-case	Z_{thjc}	–	2	K/W	$T < 1$ ms PG-TO220-7-12 package
Junction ambient	R_{thja}	–	70	K/W	PG-DSO-14-30 package
Junction-pin	R_{thjp}	–	30	K/W	PG-DSO-14-30 package

Table 6 Characteristics
 $V_1 = 13.5 \text{ V}; -40 \text{ }^\circ\text{C} < T_J < 125 \text{ }^\circ\text{C}; V_{E2} > 4 \text{ V}$ (unless specified otherwise)

Parameter	Symbol	Limit Values			Unit	Test Condition
		Min.	Typ.	Max.		
Output voltage	V_Q	4.9	5	5.1	V	$5 \text{ mA} \leq I_Q \leq 400 \text{ mA}$ $6 \text{ V} \leq V_1 \leq 26 \text{ V}$
Output voltage	V_Q	4.9	5	5.1	V	$5 \text{ mA} \leq I_Q \leq 150 \text{ mA}$ $6 \text{ V} \leq V_1 \leq 40 \text{ V}$
Output current limiting	I_Q	500	–	–	mA	$T_J = 25 \text{ }^\circ\text{C}$
Current consumption $I_q = I_1 - I_Q$	I_q	–	–	50	μA	IC turned off
Current consumption $I_q = I_1 - I_Q$	I_q	–	1.0	10	μA	$T_J = 25 \text{ }^\circ\text{C}$ IC turned off
Current consumption $I_q = I_1 - I_Q$	I_q	–	1.3	4	mA	$I_Q = 5 \text{ mA}$ IC turned on
Current consumption $I_q = I_1 - I_Q$	I_q	–	–	60	mA	$I_Q = 400 \text{ mA}$
Current consumption $I_q = I_1 - I_Q$	I_q	–	–	80	mA	$I_Q = 400 \text{ mA}$ $V_1 = 5 \text{ V}$
Drop voltage	V_{Dr}	–	0.3	0.6	V	$I_Q = 400 \text{ mA}^{1)}$
Load regulation	ΔV_Q	–	–	50	mV	$5 \text{ mA} \leq I_Q \leq 400 \text{ mA}$
Supply-voltage regulation	ΔV_Q	–	15	25	mV	$V_1 = 6 \text{ to } 36 \text{ V};$ $I_Q = 5 \text{ mA}$
Supply-voltage rejection	SVR	–	54	–	dB	$f_r = 100 \text{ Hz};$ $V_r = 0.5 \text{ Vpp}$
Longterm stability	ΔV_Q	–	0	–	mV	1000 h
Reset Generator						
Switching threshold	V_{RT}	4.2	4.5	4.8	V	–
Reset High level	–	4.5	–	–	V	$R_{ext} = \infty$
Saturation voltage	$V_{RO,SAT}$	–	0.1	0.4	V	$R_R = 4.7 \text{ k}\Omega^{2)}$
Internal Pull-up resistor	R_{RO}	–	30	–	k Ω	–
Saturation voltage	$V_{D,SAT}$	–	50	100	mV	$V_Q < V_{RT}$
Charge current	I_D	8	15	25	μA	$V_D = 1.5 \text{ V}$
Upper delay switching threshold	V_{UD}	2.6	3	3.3	V	–

Table 6 Characteristics (cont'd)

$V_I = 13.5\text{ V}$; $-40\text{ °C} < T_J < 125\text{ °C}$; $V_{E2} > 4\text{ V}$ (unless specified otherwise)

Parameter	Symbol	Limit Values			Unit	Test Condition
		Min.	Typ.	Max.		
Delay time	t_D	–	20	–	ms	$C_d = 100\text{ nF}$
Lower delay switching threshold	V_{LD}	–	0.43	–	V	–
Reset reaction time	t_{RR}	–	2	–	μs	$C_d = 100\text{ nF}$

Inhibit

Turn on voltage	$V_{U,INH}$	–	3	4	V	IC turned on
Turn off voltage	$V_{L,INH}$	2	–	–	V	IC turned off
Pull-down resistor	R_{INH}	50	100	200	$\text{k}\Omega$	–
Hysteresis	ΔV_{INH}	0.2	0.5	0.8	V	–
Input current	I_{INH}	–	35	100	μA	$V_{INH} = 4\text{ V}$
Hold voltage	$V_{U,HOLD}$	30	35	40	%	Referred to V_Q
Turn off voltage	$V_{L,HOLD}$	60	70	80	%	Referred to V_Q
Pull-up resistor	R_{HOLD}	20	50	100	$\text{k}\Omega$	–

Overvoltage Protection

Turn off voltage	$V_{I,OV}$	42	44	46	V	V_I increasing
Turn on voltage	$V_{I,turn\ on}$	36	–	–	V	V_I decreasing after turn off

1) Drop voltage = $V_I - V_Q$ (measured when the output voltage V_Q has dropped 100 mV from the nominal value obtained at $V_I = 13.5\text{ V}$)

2) The reset output is Low for $1\text{ V} < V_Q < V_{RT}$

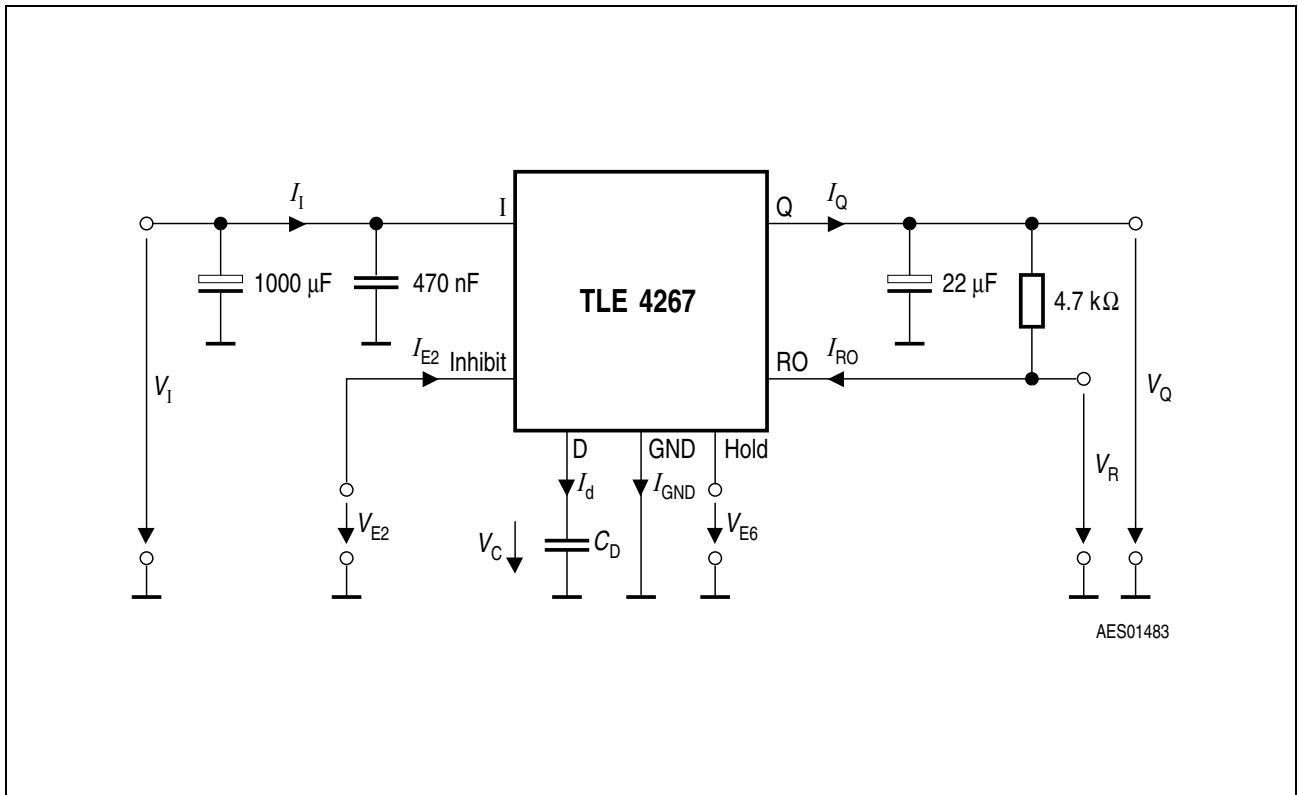


Figure 4 Test Circuit

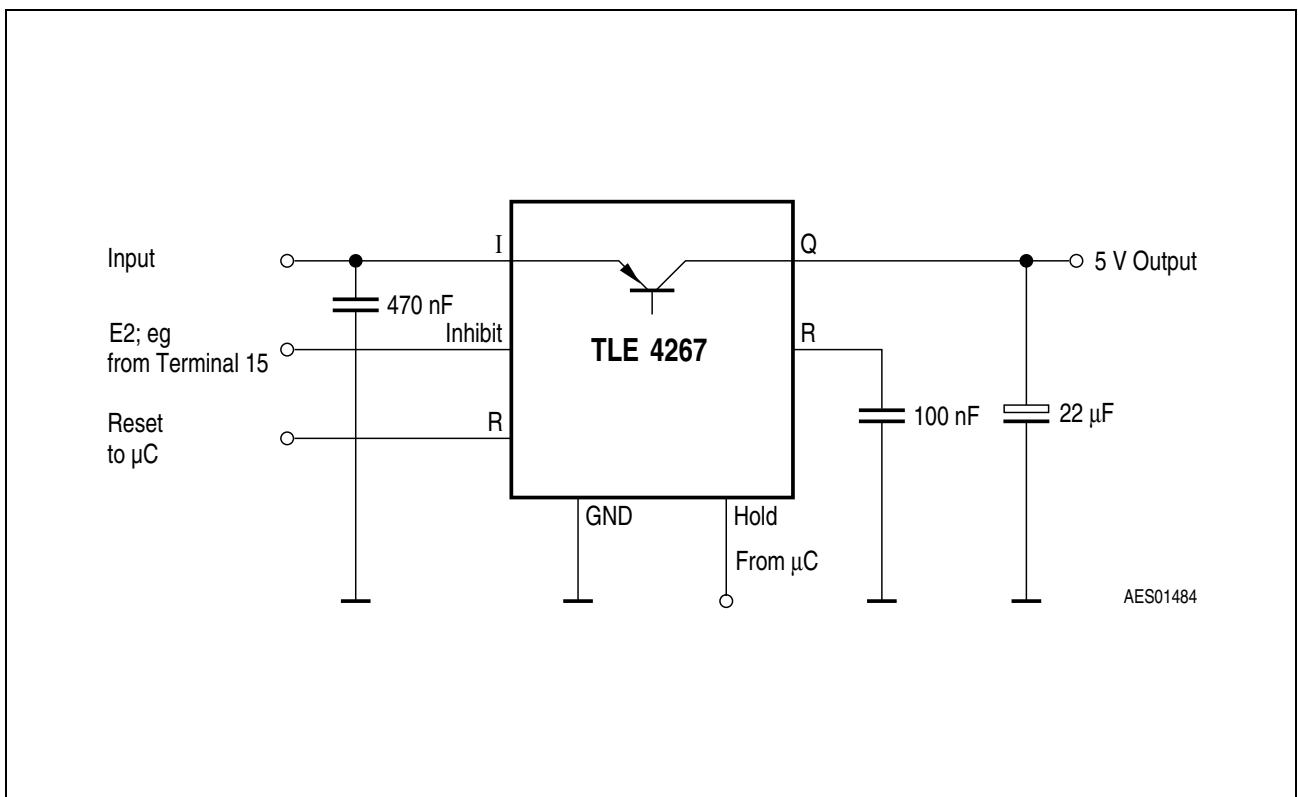


Figure 5 Application Circuit

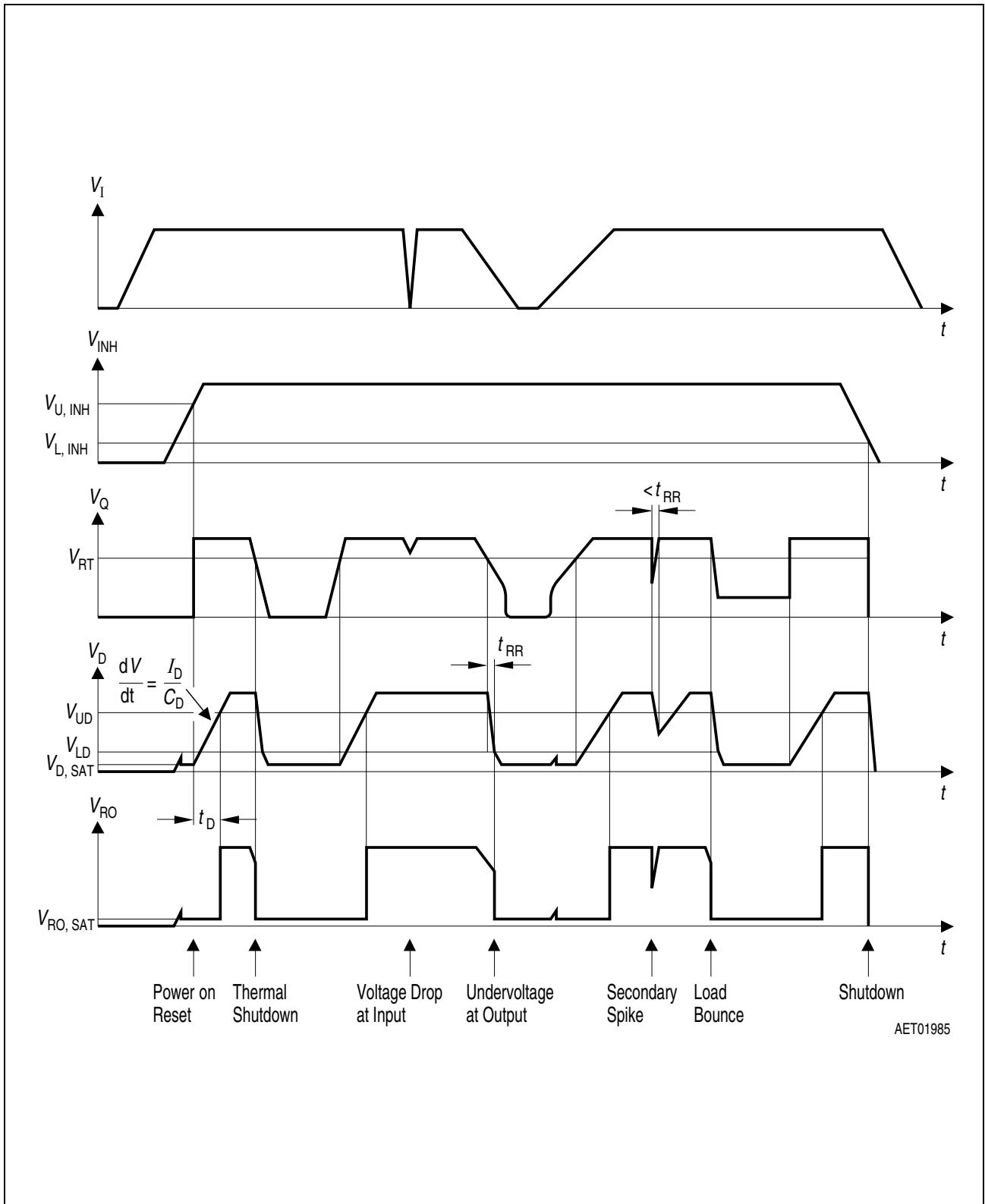


Figure 6 Time Response

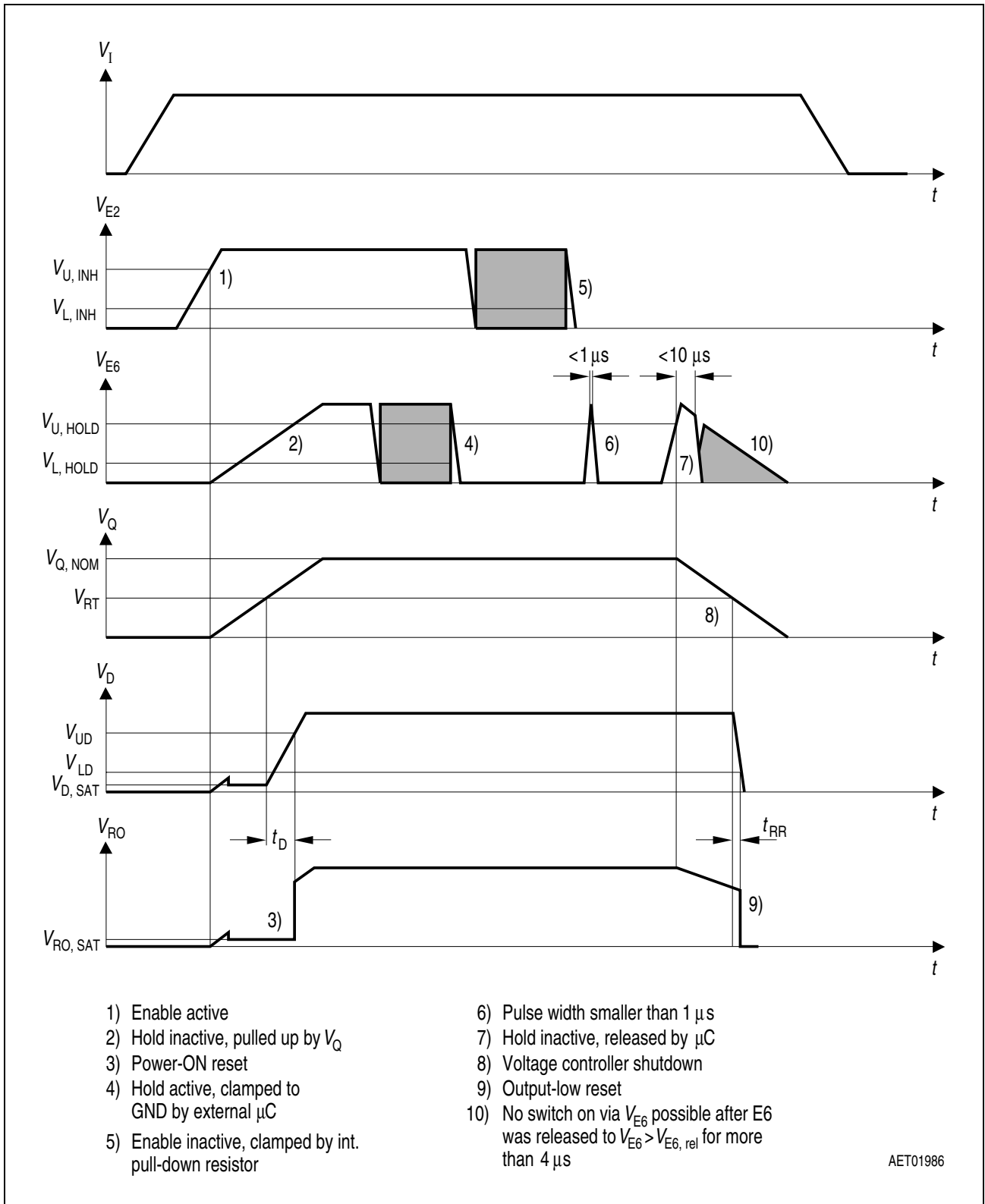
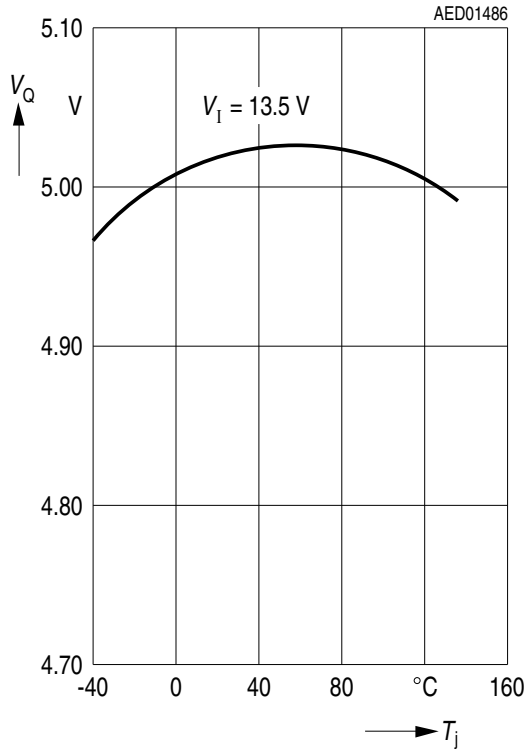
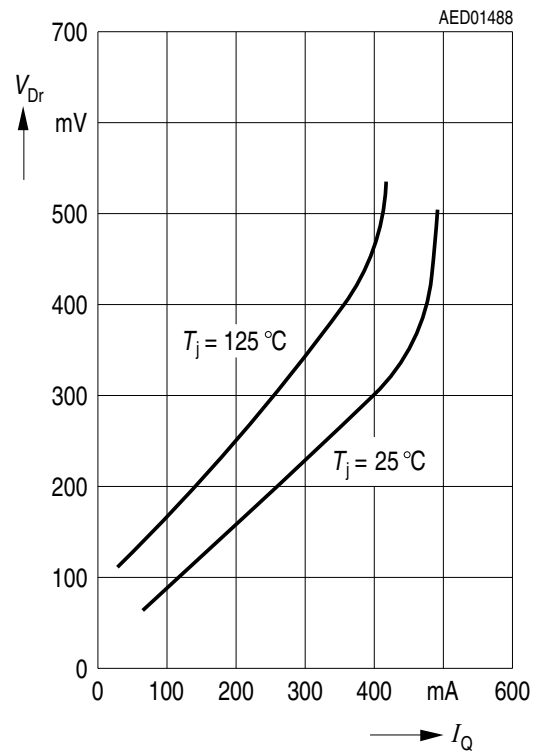


Figure 7 Enable and Hold Behavior

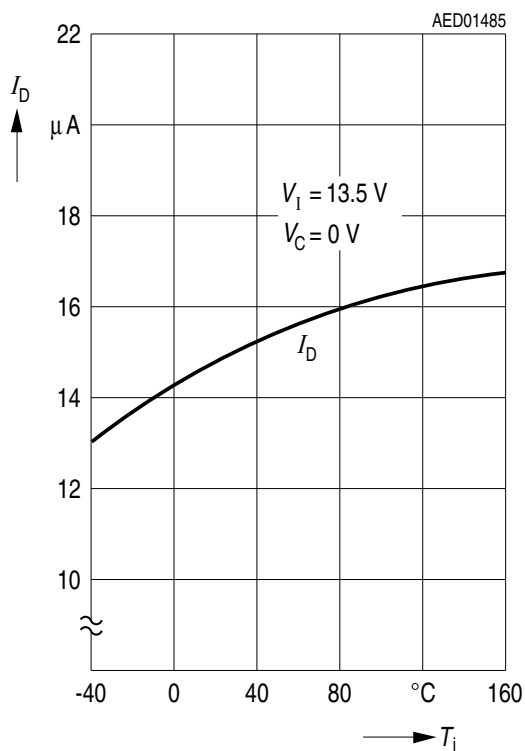
Output Voltage V_Q versus Temperature T_j



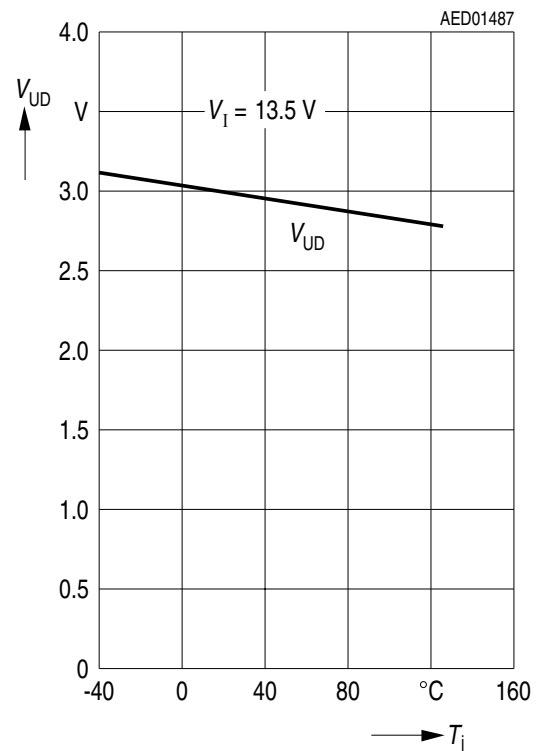
Drop Voltage V_{Dr} versus Output Current I_Q



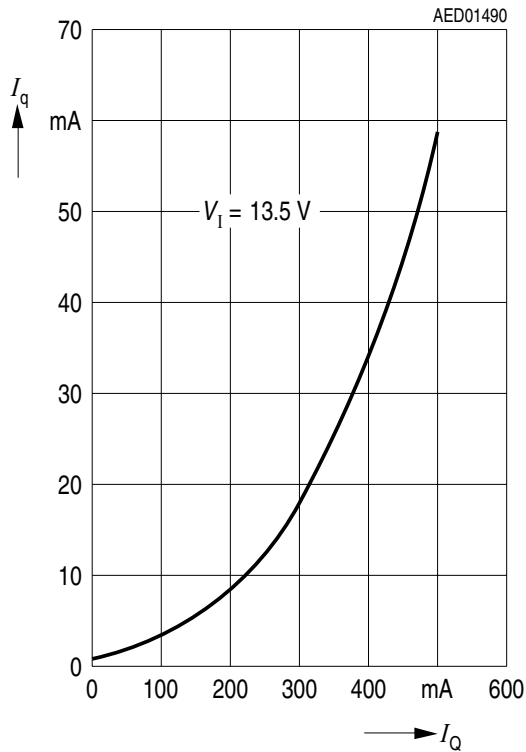
Charge Current I_D versus Temperature T_j



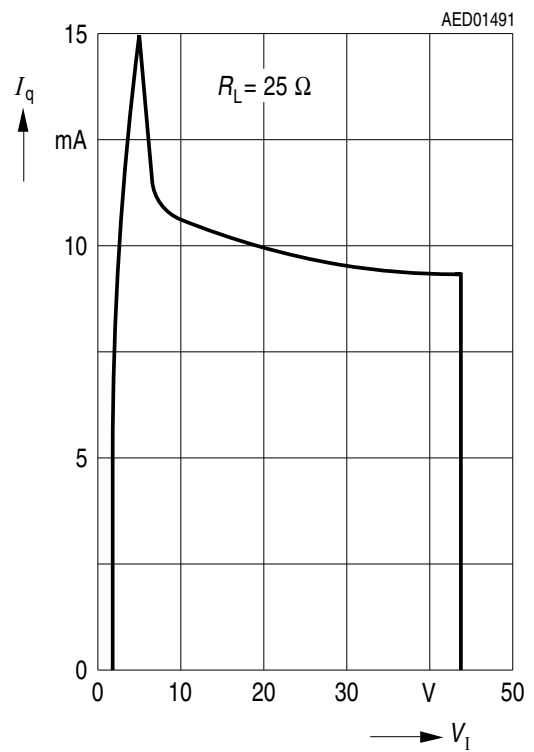
Delay Switching Threshold V_{UD} versus Temperature T_j



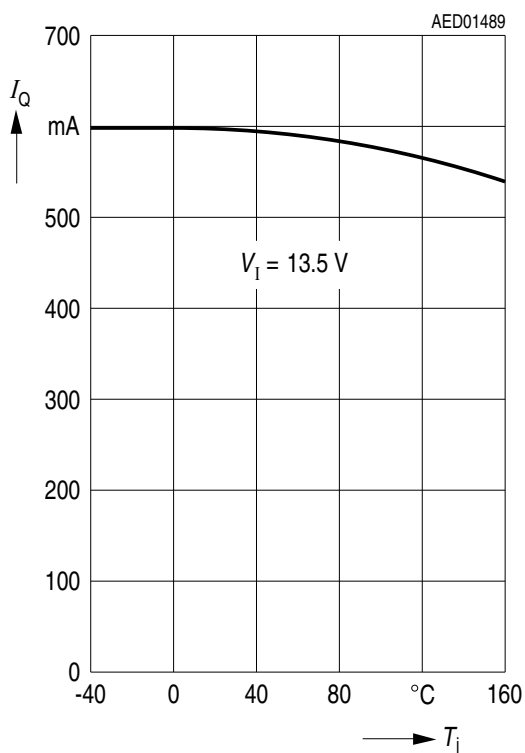
Current Consumption I_q versus Output Current I_Q



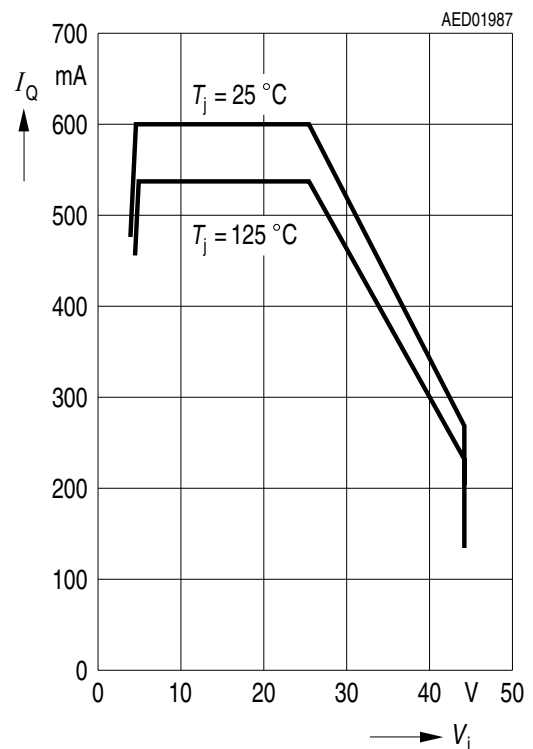
Current Consumption I_q versus Input Voltage V_I



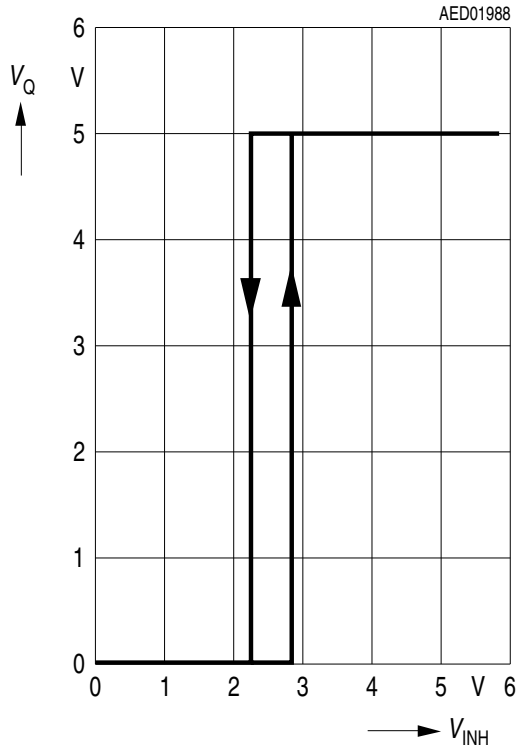
Output Current Limiting I_Q versus Temperature T_j



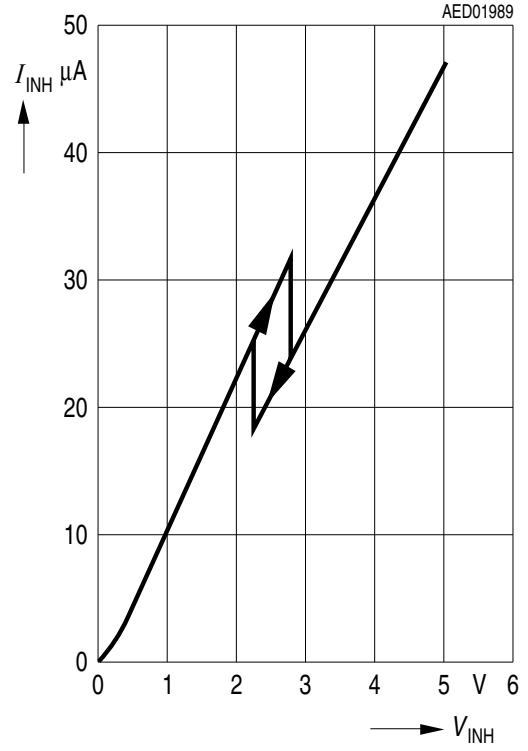
Output Current Limiting I_Q versus Input Voltage V_I



Output Voltage V_Q versus Inhibit Voltage V_{INH}



Inhibit Current I_{INH} versus Inhibit Voltage V_{INH}



Package Outlines

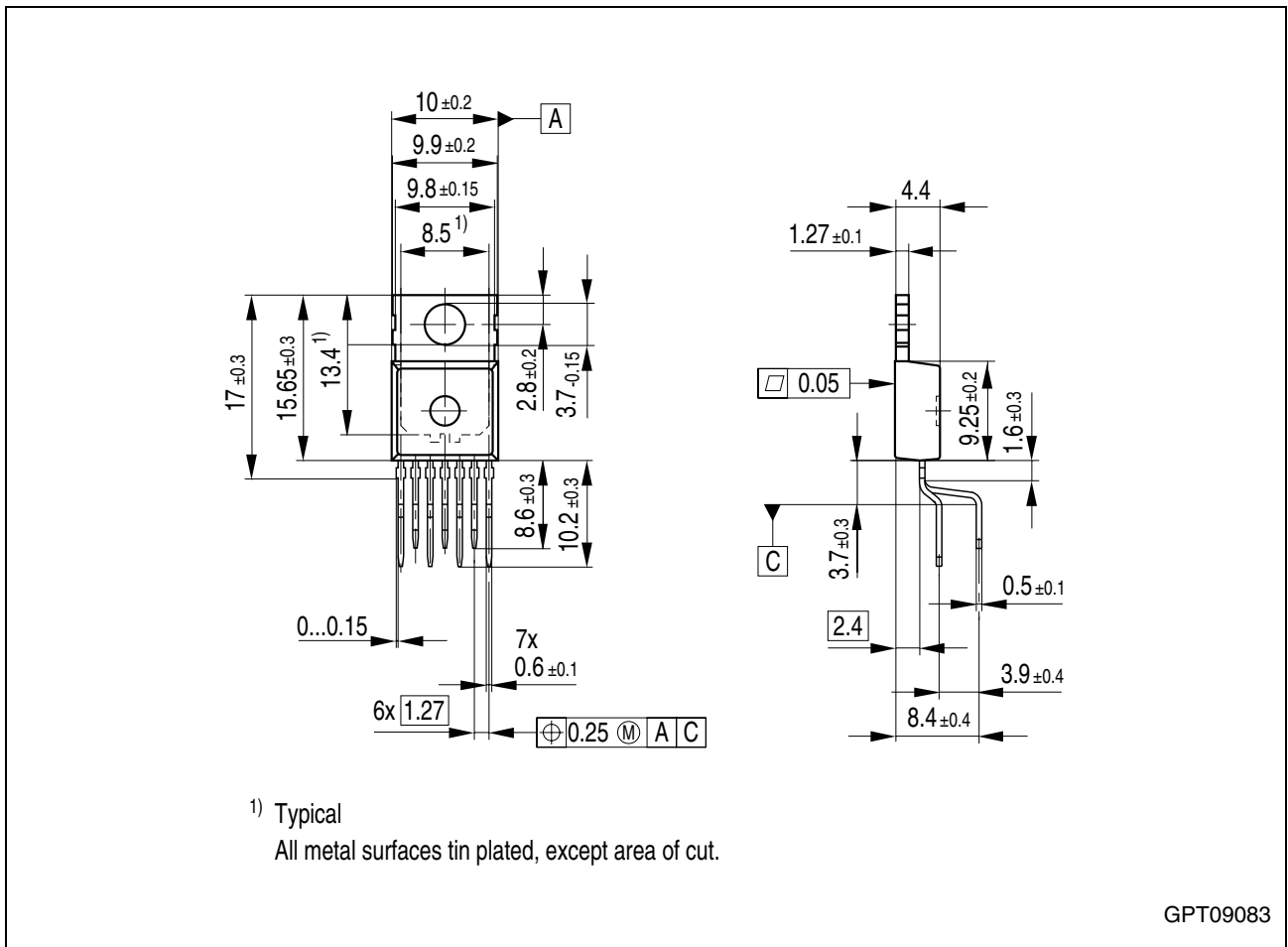


Figure 8 PG-TO220-7-11 (Plastic Transistor Single Outline)

Green Product (RoHS compliant)

To meet the world-wide customer requirements for environmentally friendly products and to be compliant with government regulations the device is available as a green product. Green products are RoHS-Compliant (i.e Pb-free finish on leads and suitable for Pb-free soldering according to IPC/JEDEC J-STD-020).

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SMD = Surface Mounted Device

Dimensions in mm

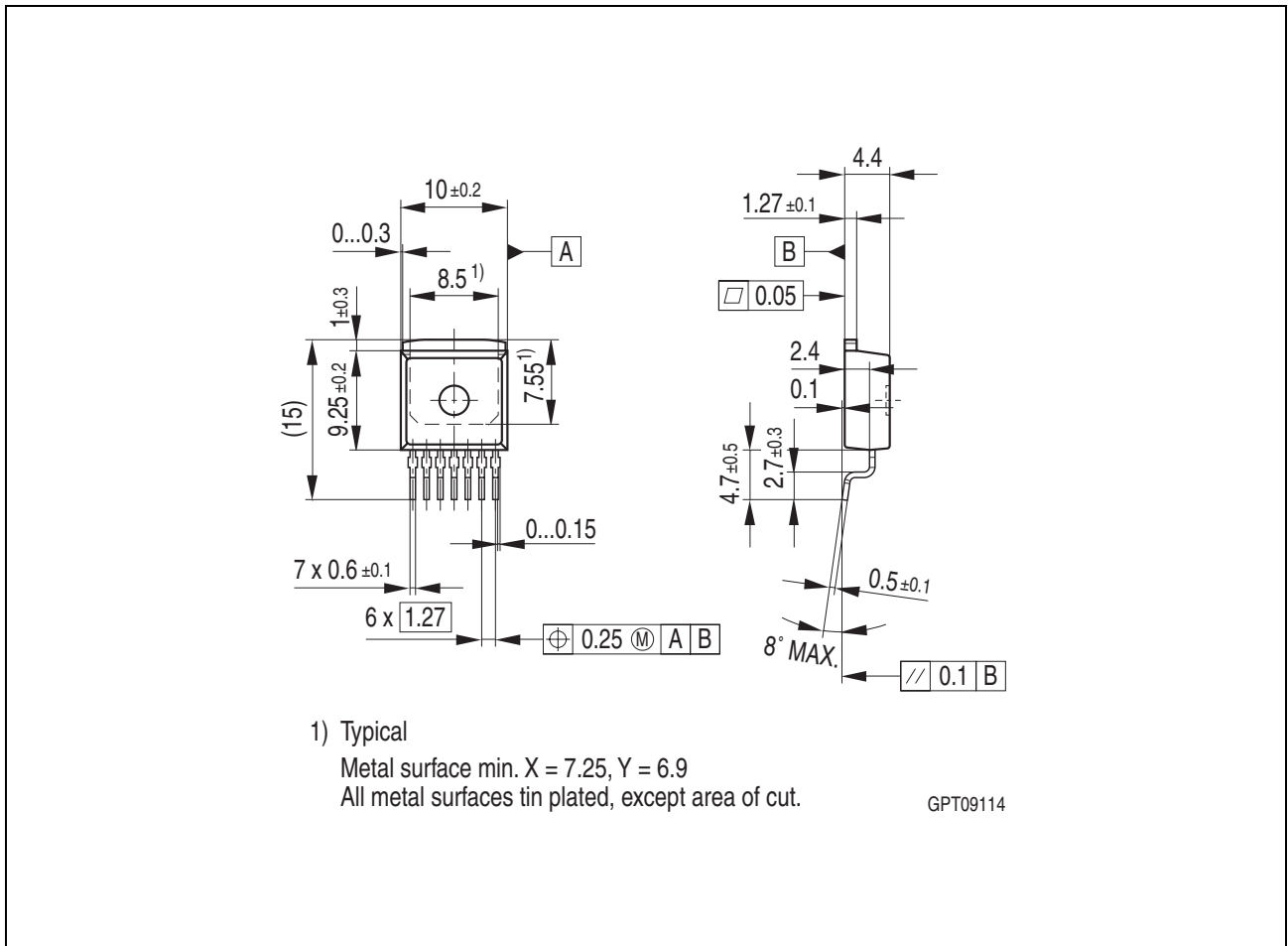


Figure 9 PG-TO263-7-1 (Plastic Transistor Single Outline)

Green Product (RoHS compliant)

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SMD = Surface Mounted Device

Dimensions in mm

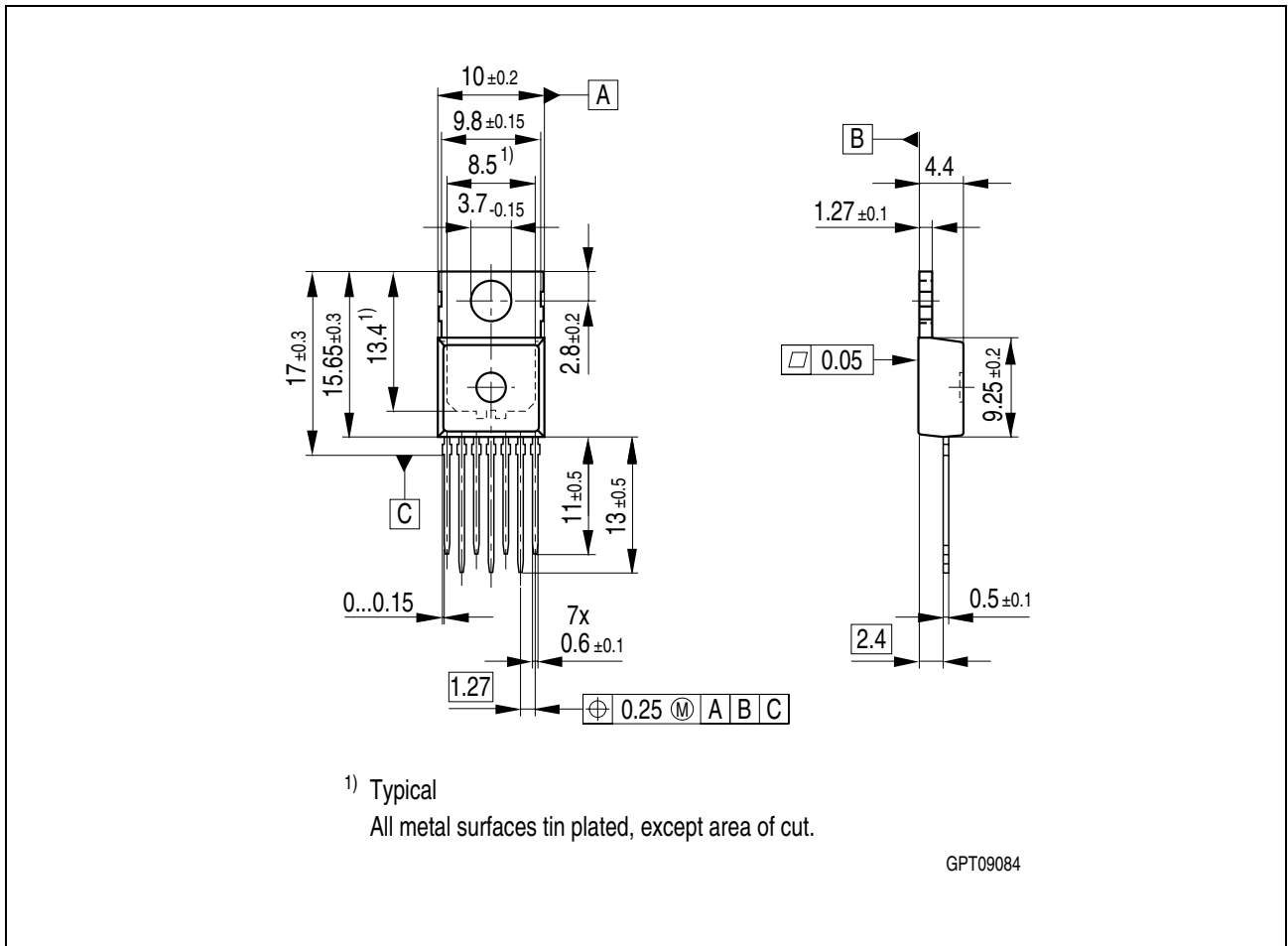


Figure 10 PG-TO220-7-12 (Plastic Transistor Single Outline)

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SMD = Surface Mounted Device

Dimensions in mm

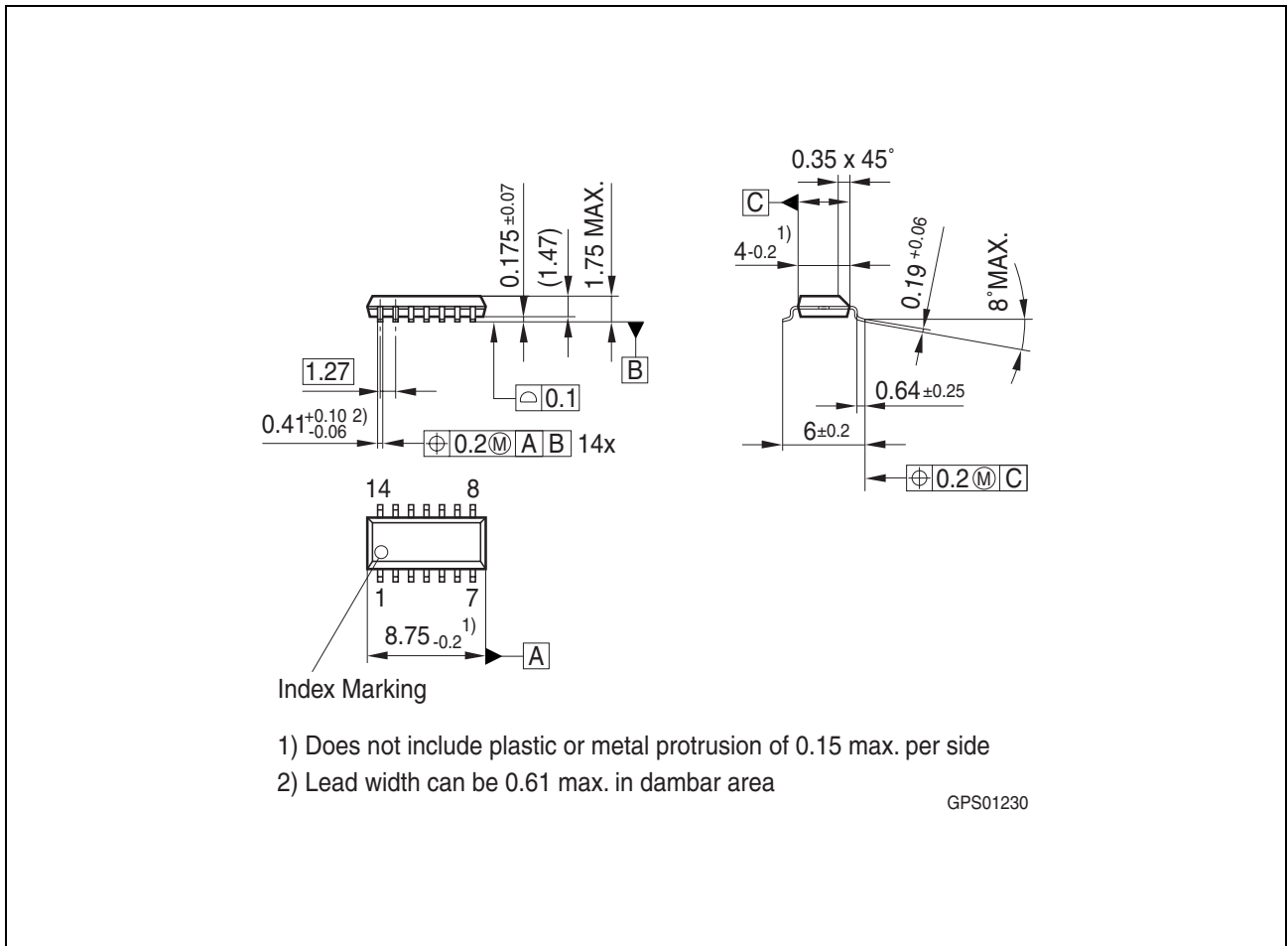


Figure 11 PG-DSO-14-30 (Plastic Dual Small Outline)

Green Product (RoHS compliant)

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SMD = Surface Mounted Device

Dimensions in mm

Revision History

Version	Date	Changes
Rev. 2.5	2007-03-20	Initial version of RoHS-compliant derivate of TLE 4267 Page 1 : AEC certified statement added Page 1 and Page 17 ff: RoHS compliance statement and Green product feature added Page 1 and Page 17 ff: Package changed to RoHS compliant version Legal Disclaimer updated

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